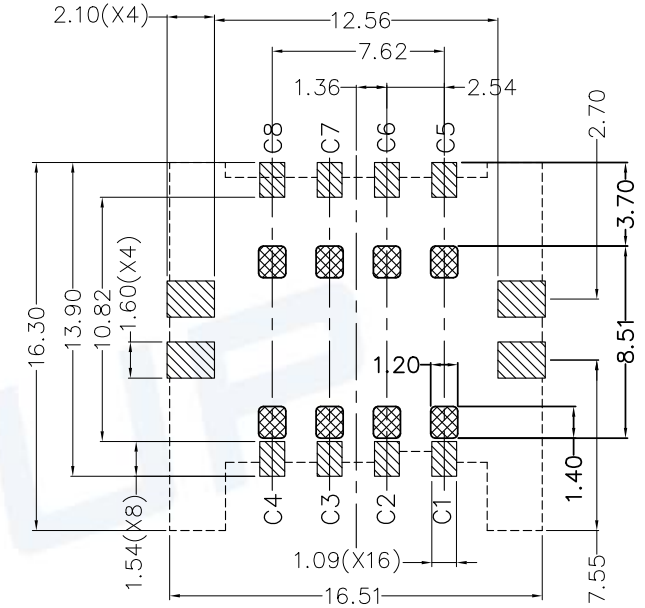
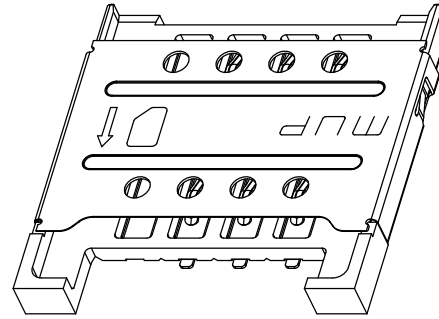
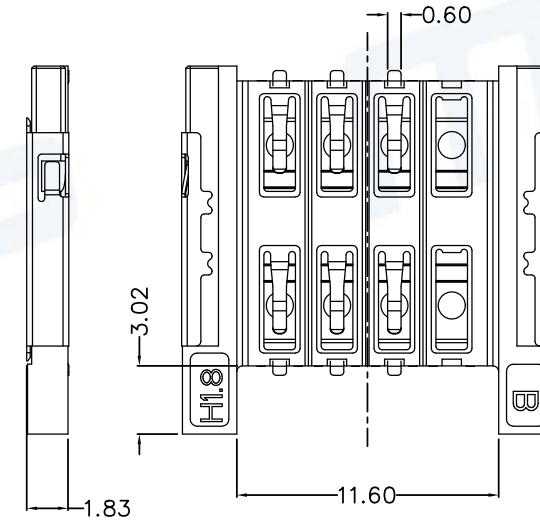
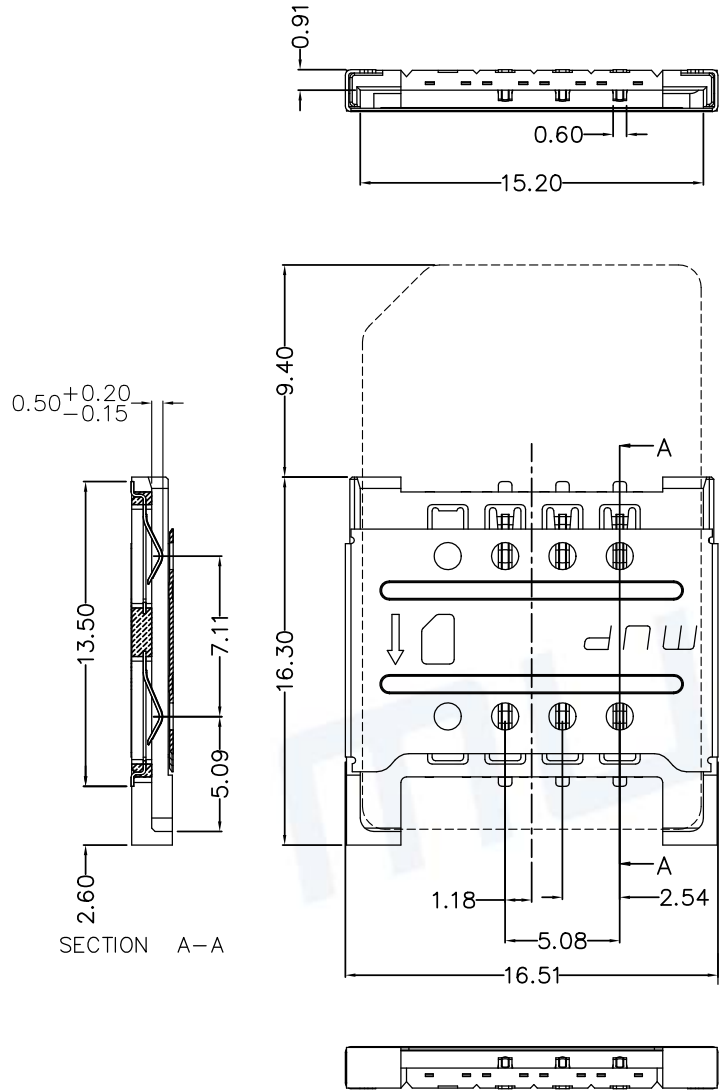


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					



RECOMMENDED P.C.B LAYOUT  
COMPONENT SIDE(TOLERANCE  $\pm 0.05$ )



#### TECHNICAL CHARACTERISTICS

##### 1.General Characteristics

Dimensions: 16.51LX16.30WX1.80H mm  
Weight: Approx g  
Durability: 5,000 cycles min.

##### 2.Electrical Characteristics

Contact resistance: 50m $\Omega$  typical, 100m $\Omega$  max  
Insulation resistance: >1000M $\Omega$ /500V DC

##### 3.Solderability

Vaporphase: 215°C, 30sec.Max  
IR reflow: 250°C, 5sec.Max  
Manual soldering: 370°C, 3sec.Max

##### 4.Environmental Characteristics

Operating temperature: -40°C~+85°C  
Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	SMT area:Gold plated

Unless otherwise specified, other tolerance are:

X	$\pm 0.35$	X'	$\pm 5'$
X.X	$\pm 0.25$	X.X'	$\pm 4'$
X.XX	$\pm 0.15$	X.XX'	$\pm 3'$
X.XXX	$\pm 0.10$	X.XXX'	$\pm 2'$

**MUP** MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**  
MODEL NO: **MUP-C708-5**  
TYPE: **H1.80 Without post 6P**

PROJ.	UNIT	SCALE
	mm	1:1

DRAWN	Jimmy 5/10-17'	DWG NO.:	DWG-MUP-C708-005
CHECKED	Sean 5/10-17'	SHEET	1/1
APPROVAL	Simon 5/10-17'	REVISION	X1

CUSTOMER DRAWING

